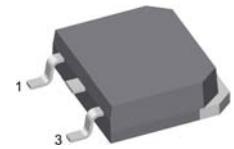
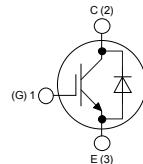


**XPT IGBT**

Copack

**I<sub>C25</sub>** = **20 A**  
**V<sub>CES</sub>** = **1200 V**  
**V<sub>CE(sat)typ</sub>** = **1.8 V**

**Part number****IXA12IF1200TC****Features / Advantages:**

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
  - short circuit rated for 10  $\mu$ sec.
  - very low gate charge
  - low EMI
  - square RBSOA @ 3x I<sub>c</sub>
- Thin wafer technology combined with the XPT design results in a competitive low V<sub>CE(sat)</sub>
- SONIC™ diode
  - fast and soft reverse recovery
  - low operating forward voltage

**Applications:**

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers

**Package:**

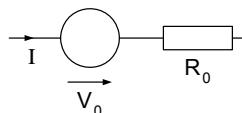
- Housing: TO-268AA (D3Pak)
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

**IGBT****Ratings**

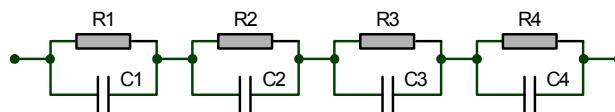
| Symbol               | Definition                           | Conditions   | min.                    | typ. | max.     | Unit    |   |
|----------------------|--------------------------------------|--|-------------------------|------|----------|---------|---|
| V <sub>CES</sub>     | Collector emitter voltage            | V <sub>GE</sub> = 0 V  | T <sub>VJ</sub> = 25°C  |      | 1200     | V       |   |
| V <sub>GES</sub>     | Maximum DC gate voltage              |  | T <sub>VJ</sub> = 25°C  |      | $\pm 20$ | V       |   |
| I <sub>C25</sub>     | Collector current                    |  | T <sub>C</sub> = 25°C   |      | 20       | A       |   |
| I <sub>C90</sub>     |                                      |  | T <sub>C</sub> = 90°C   |      | 13       | A       |   |
| P <sub>tot</sub>     | Total power dissipation              |  | T <sub>VJ</sub> = 25°C  |      | 85       | W       |   |
| I <sub>CES</sub>     | Collector emitter leakage current    | V <sub>CE</sub> = V <sub>CES</sub> ; V <sub>GE</sub> = 0 V                         | T <sub>VJ</sub> = 25°C  |      | 0.1      | mA      |   |
|                      |                                      |  | T <sub>VJ</sub> = 125°C |      | 0.1      | mA      |   |
| I <sub>GES</sub>     | Gate emitter leakage current         | V <sub>CE</sub> = 0 V; V <sub>GE</sub> = $\pm 20$ V                                |                         |      | 500      | nA      |   |
| V <sub>CE(sat)</sub> | Collector emitter saturation voltage | I <sub>C</sub> = 9 A; V <sub>GE</sub> = 15 V                                       | T <sub>VJ</sub> = 25°C  | 1.8  | 2.1      | V       |   |
|                      |                                      |  | T <sub>VJ</sub> = 125°C | 2.1  |          | V       |   |
| V <sub>GE(th)</sub>  | Gate emitter threshold voltage       | I <sub>C</sub> = 0.3 mA; V <sub>GE</sub> = V <sub>CE</sub>                         |                         | 5.5  | 6        | 6.5     | V |
| Q <sub>Gon</sub>     | Total gate charge                    | V <sub>CE</sub> = 600 V; V <sub>GE</sub> = 15 V; I <sub>C</sub> = 10 A             |                         |      | 27       | nC      |   |
| t <sub>d(on)</sub>   | Turn-on delay time                   |  |                         |      | 70       | ns      |   |
| t <sub>r</sub>       | Current rise time                    |  |                         |      | 40       | ns      |   |
| t <sub>d(off)</sub>  | Turn-off delay time                  | Inductive load   |                         |      | 250      | ns      |   |
| t <sub>f</sub>       | Current fall time                    | V <sub>CE</sub> = 600 V; I <sub>C</sub> = 10 A                                     |                         |      | 100      | ns      |   |
| E <sub>on</sub>      | Turn-on energy per pulse             | V <sub>GE</sub> = $\pm 15$ V; R <sub>G</sub> = 100 $\Omega$                        | T <sub>VJ</sub> = 125°C |      | 1.1      | mJ      |   |
| E <sub>off</sub>     | Turn-off energy per pulse            |  |                         |      | 1.1      | mJ      |   |
| RBSOA                | Reverse bias safe operation area     | V <sub>GE</sub> = 15 V; R <sub>G</sub> = 100 $\Omega$<br>V <sub>CEK</sub> = 1200 V | T <sub>VJ</sub> = 125°C |      | 30       | A       |   |
| SCSOA                | Short circuit safe operation area    |  |                         |      |          |         |   |
| t <sub>sc</sub>      | Short circuit duration               | V <sub>CE</sub> = 900 V; V <sub>GE</sub> = $\pm 15$ V                              | T <sub>VJ</sub> = 125°C |      | 10       | $\mu$ s |   |
| I <sub>sc</sub>      | Short circuit current                | R <sub>G</sub> = 100 $\Omega$ ; non-repetitive                                     |                         |      | 40       | A       |   |
| R <sub>thJC</sub>    | Thermal resistance junction to case  |  |                         |      | 1.5      | K/W     |   |

**Diode**

| Symbol         | Definition                          | Conditions              | Ratings                |      |      |         |
|----------------|-------------------------------------|-------------------------|------------------------|------|------|---------|
|                |                                     |                         | min.                   | typ. | max. | Unit    |
| $I_{F25}$      | Forward current                     | $T_C = 25^\circ C$      |                        |      | 22   | A       |
| $I_{F90}$      |                                     | $T_C = 90^\circ C$      |                        |      | 14   | A       |
| $V_F$          | Forward voltage                     | $I_F = 10 A$            | $T_{VJ} = 25^\circ C$  | 1.95 | 2.2  | V       |
|                |                                     |                         | $T_{VJ} = 125^\circ C$ | 1.85 |      | V       |
| $Q_{rr}$       | Reverse recovery charge             |                         |                        | tbd  |      | $\mu C$ |
| $I_{RM}$       | Maximum reverse recovery current    | $V_R = 600V$ ;          |                        | tbd  |      | A       |
| $t_{rr}$       | Reverse recovery time               | $di_F/dt = - A/\mu s$ ; | $T_{VJ} = 125^\circ C$ | tbd  |      | ns      |
| $E_{rec(off)}$ | Reverse recovery losses at turn-off | $I_F = 10 A$            |                        | tbd  |      | mJ      |
| $R_{thJC}$     | Thermal resistance junction to case |                         |                        |      | 1.8  | K/W     |

**Equivalent Circuits for Simulation****Ratings**

| Symbol | Definition |                        | min. | typ. | max. | Unit      |
|--------|------------|------------------------|------|------|------|-----------|
| $V_0$  | IGBT       | $T_{VJ} = 150^\circ C$ |      |      | 1.1  | V         |
| $R_0$  |            |                        |      |      | 153  | $m\Omega$ |
| $V_0$  | Diode      | $T_{VJ} = 150^\circ C$ |      |      | 1.1  | V         |
| $R_0$  |            |                        |      |      | 90   | $m\Omega$ |



$$Z_{th}(t) = \sum_{i=1}^n \left[ R_i \cdot \left( 1 - \exp\left(-\frac{t}{\tau_i}\right) \right) \right]$$

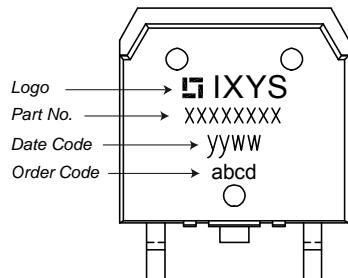
$$\tau_i = R_i \cdot C_i$$

|          | IGBT | Diode |
|----------|------|-------|
| $R_1$    | tbd  | tbd   |
| $R_2$    | tbd  | tbd   |
| $R_3$    | tbd  | tbd   |
| $R_4$    | tbd  | tbd   |
| $\tau_1$ | tbd  | tbd   |
| $\tau_2$ | tbd  | tbd   |
| $\tau_3$ | tbd  | tbd   |
| $\tau_4$ | tbd  | tbd   |

## Package TO-268AA (D3Pak)

| Symbol            | Definition                          | Conditions | Ratings |      |      |     |
|-------------------|-------------------------------------|------------|---------|------|------|-----|
|                   |                                     |            | min.    | typ. | max. |     |
| T <sub>VJ</sub>   | Virtual junction temperature        |            | -55     |      | 150  | °C  |
| T <sub>stg</sub>  | Storage temperature                 |            | -55     |      | 150  | °C  |
| R <sub>thCH</sub> | Thermal resistance case to heatsink |            |         | 0.15 |      | K/W |
| Weight            |                                     |            |         | 5    |      | g   |
| F <sub>c</sub>    | Mounting force with clip            |            | 20      |      | 120  | N   |

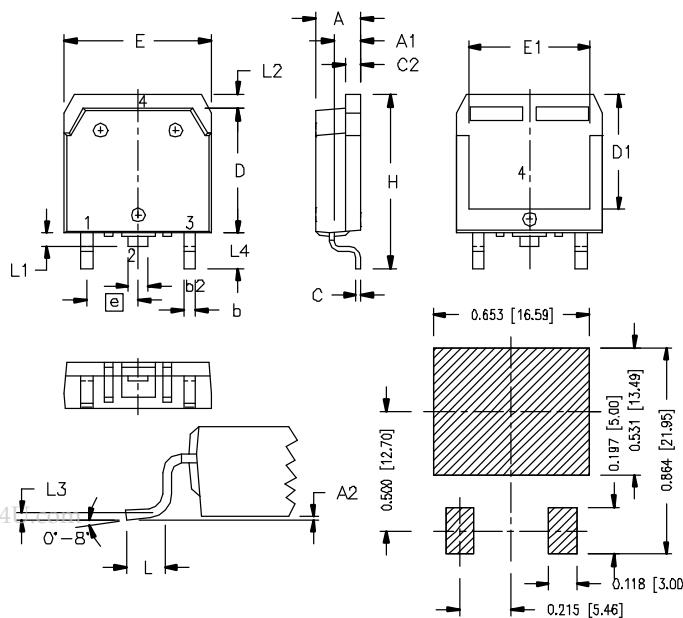
## Product Marking



## Part number

I = IGBT  
 X = XPT IGBT  
 A = Gen 1 / std  
 12 = Current Rating [A]  
 IF = Copack  
 1200 = Reverse Voltage [V]  
 TC = TO-268AA (D3Pak) (2)

| Ordering | Part Name         | Marking on Product | Delivering Mode | Base Qty | Code Key |
|----------|-------------------|--------------------|-----------------|----------|----------|
| Standard | IXA 12 IF 1200 TC | IXA12IF1200TC      |                 |          |          |



| SYM | INCHES |      | MILLIMETERS |       |
|-----|--------|------|-------------|-------|
|     | MIN    | MAX  | MIN         | MAX   |
| A   | .193   | .201 | 4.90        | 5.10  |
| A1  | .106   | .114 | 2.70        | 2.90  |
| A2  | .001   | .010 | 0.02        | 0.25  |
| b   | .045   | .057 | 1.15        | 1.45  |
| b2  | .075   | .083 | 1.90        | 2.10  |
| C   | .016   | .026 | 0.40        | 0.65  |
| C2  | .057   | .063 | 1.45        | 1.60  |
| D   | .543   | .551 | 13.80       | 14.00 |
| D1  | .488   | .500 | 12.40       | 12.70 |
| E   | .624   | .632 | 15.85       | 16.05 |
| E1  | .524   | .535 | 13.30       | 13.60 |
| e   | .215   | BSC  | 5.45        | BSC   |
| H   | .736   | .752 | 18.70       | 19.10 |
| L   | .094   | .106 | 2.40        | 2.70  |
| L1  | .047   | .055 | 1.20        | 1.40  |
| L2  | .039   | .045 | 1.00        | 1.15  |
| L3  | .010   | BSC  | 0.25        | BSC   |
| L4  | .150   | .161 | 3.80        | 4.10  |

RECOMMENDED MINIMUM FOOT PRINT FOR SMD

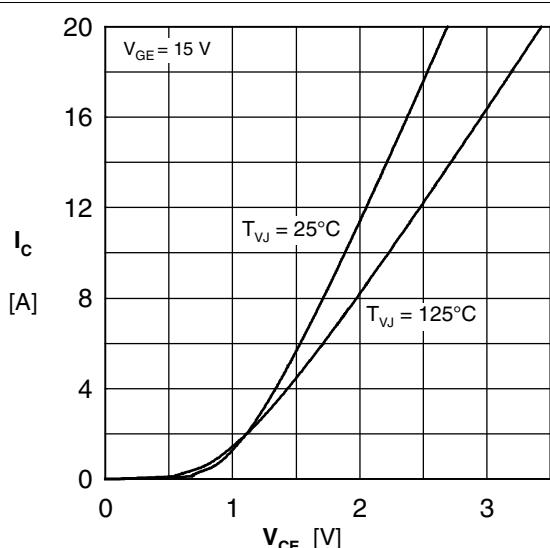


Fig. 1 Typ. output characteristics

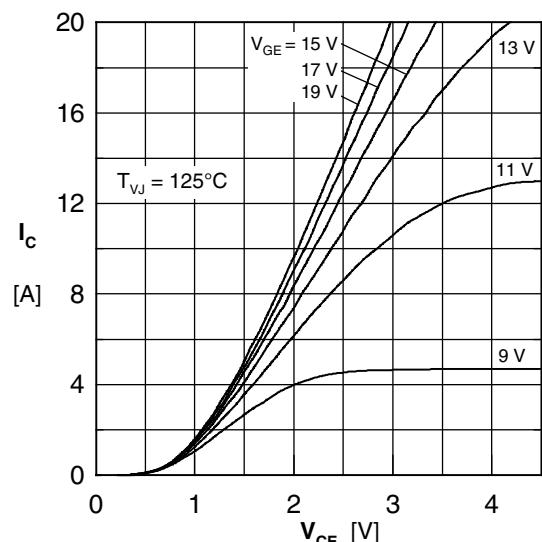


Fig. 2 Typ. output characteristics

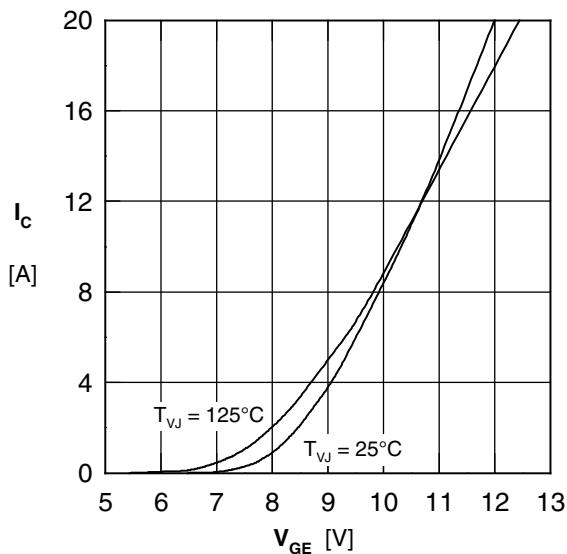


Fig. 3 Typ. tranfer characteristics

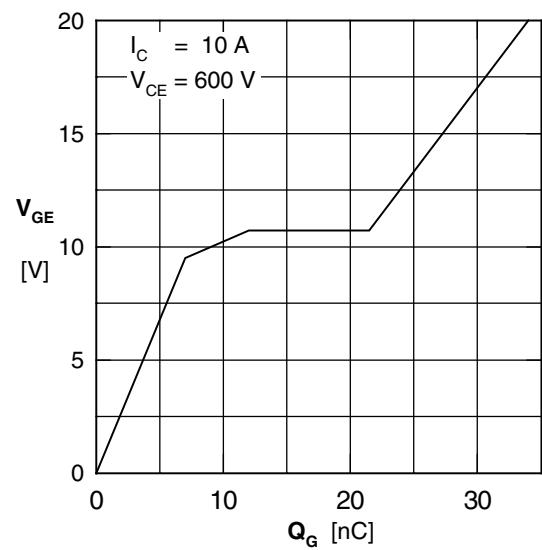


Fig. 4 Typ. turn-on gate charge

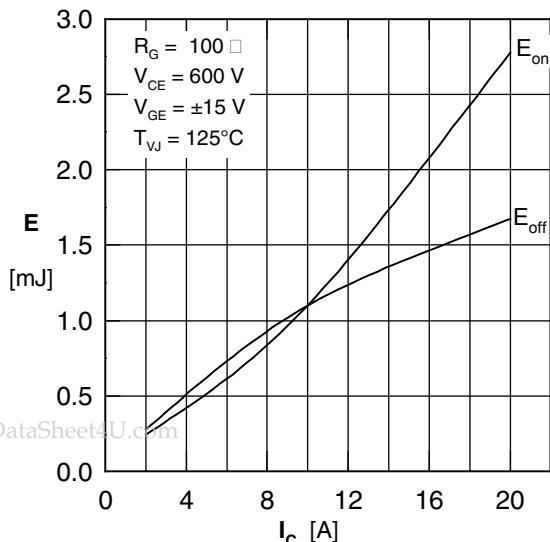


Fig. 5 Typ. switching energy vs. collector current

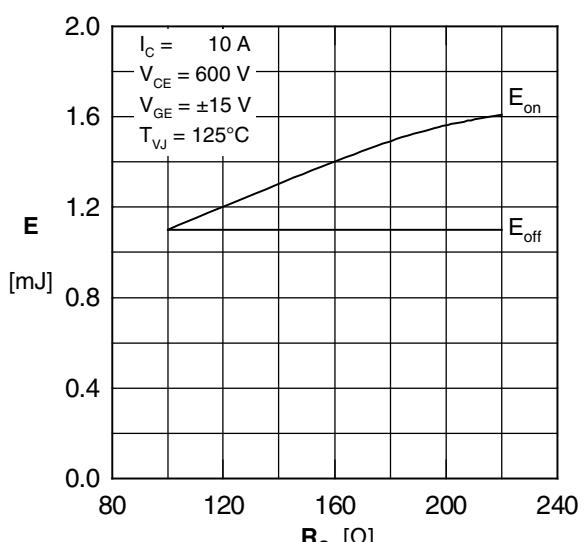


Fig. 6 Typ. switching energy vs. gate resistance

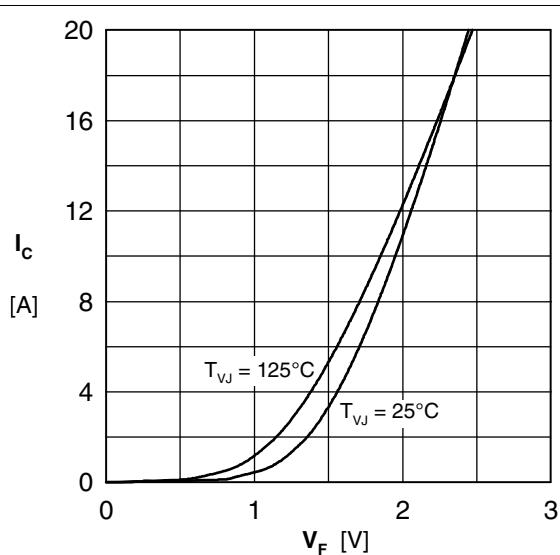


Fig. 7 Typ. forward characteristic